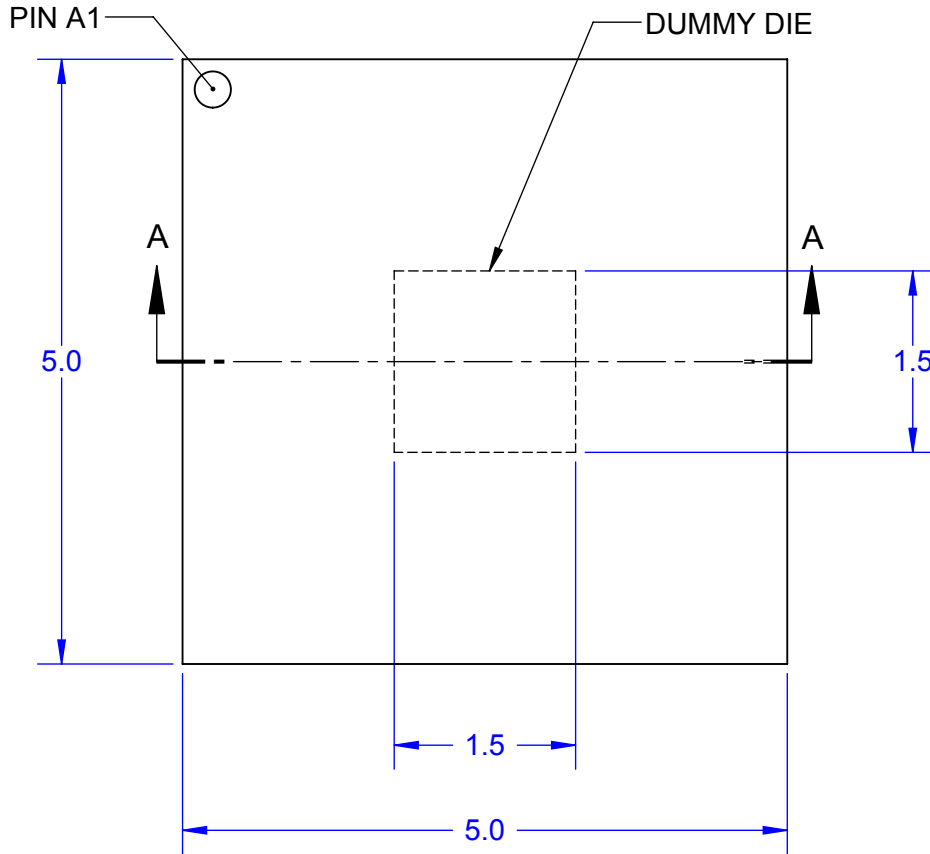
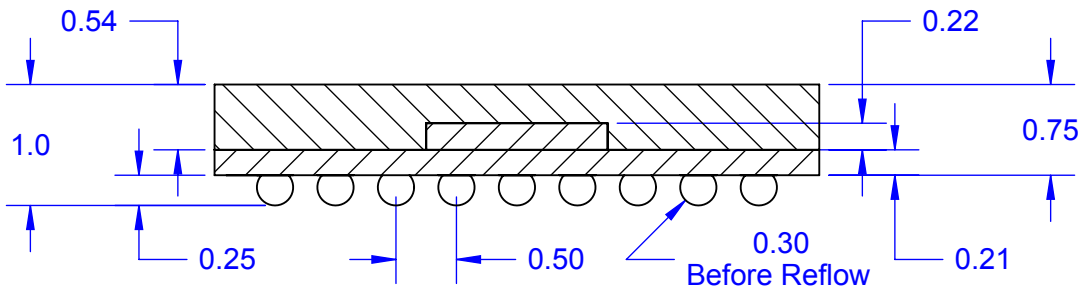
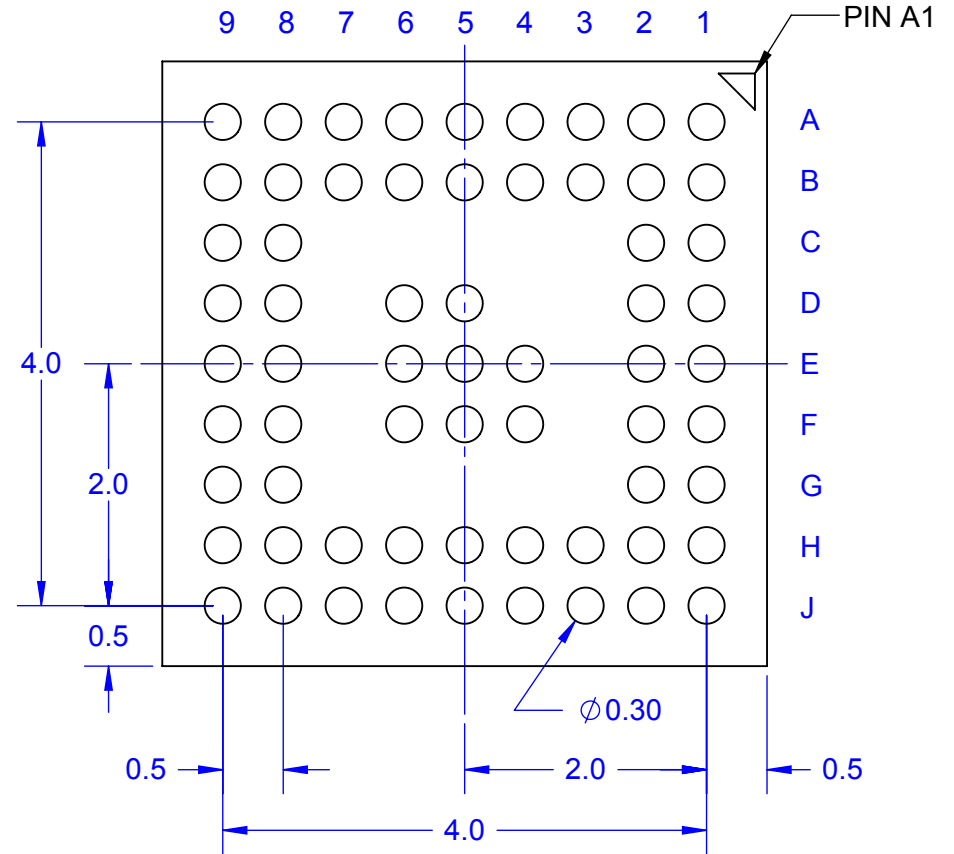


TOP VIEW




BALL VIEW

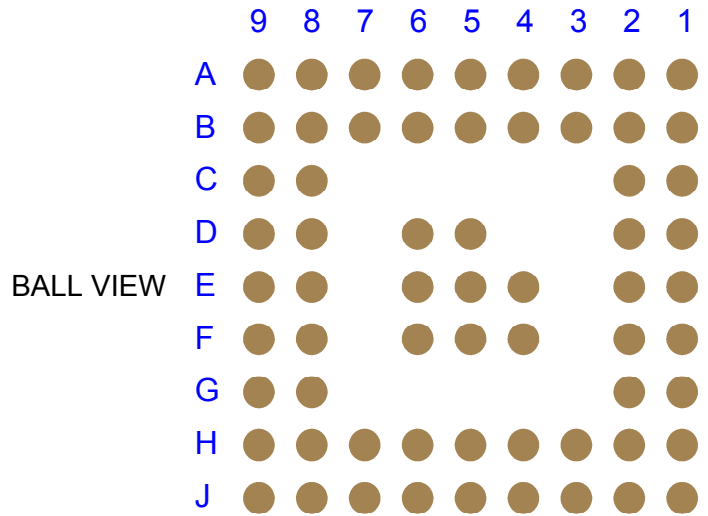


SECTION A-A

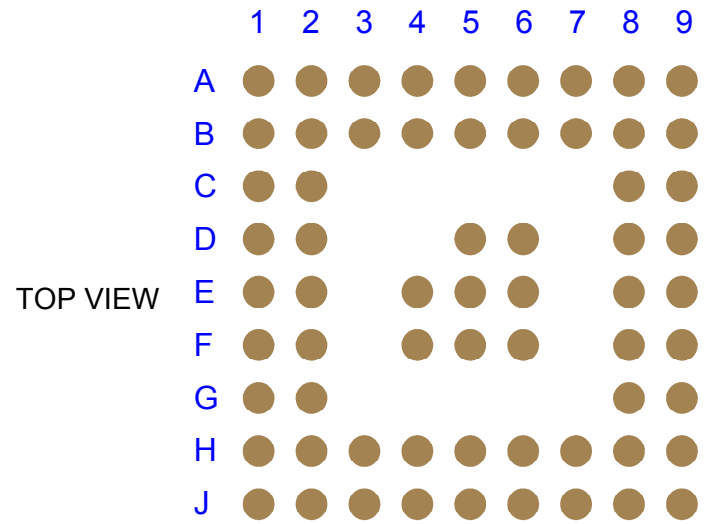
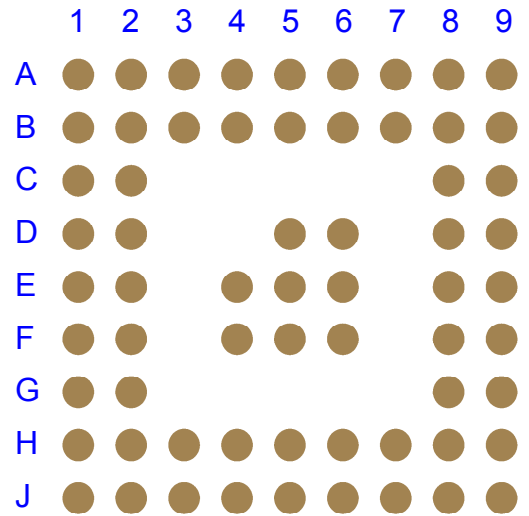
- Notes: (Unless Otherwise Specified).
 1) ALL DIMENSIONS ARE IN MM.
 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
 3) BALL DIAMETER (BEFORE REFLOW): 0.30mm.
 4) SOLDER MASK DEFINED PAD OPENING: 0.254mm [10 MIL].
 5) PAD Cu DIAMETER: 0.30mm [12 MIL].
 6) SUBSTRATE MATERIAL: BT.
 7) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE					
PART NUMER	BALL ALLOY	Pb-FREE	RoHS	Si DIE	Pack
BGA64T.5C-9x9-D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES	TRAY
BGA64E13A.5C-9x9-D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES	REEL

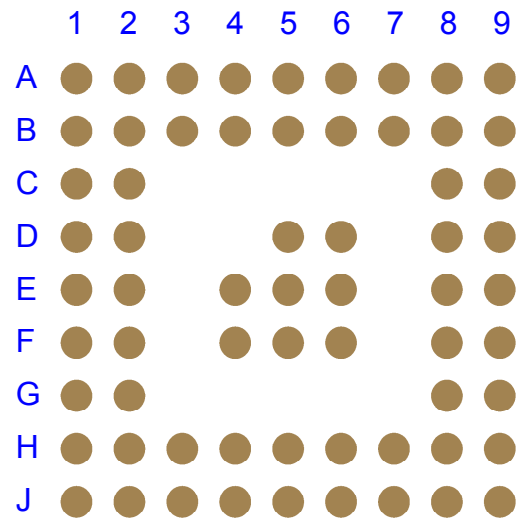
APPROVALS	DATE				
DRAWN T.Au	04/22/14				
ENG M. Hart	04/22/14	TITLE BGA64T.5C-9x9-D DAISY CHAIN DUMMY			
MFG		SCALE 15:1	SIZE A	DRAWING NO. 550920	REV A
QA		DO NOT SCALE DRAWING			SHEET 1 OF 2
CUST					
REVISED					



BOTTOM SIDE
(TOP X-RAY VIEW)



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



- Notes:
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
 - 2) PCB Cu BALL PAD DIAMETER 0.30mm [12 MIL].
 - 3) SMD (SOLDER MASK DEFINED) PAD OPENING 0.254mm [10 MIL].

TopLine®			
TITLE		BGA64T.5C-9x9-D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
14:1	A	550920	A
DO NOT SCALE DRAWING			SHEET 2 OF 2